

Session Program

30 September 2024 to 4 October 2024



TWEPP 2024 Topical Workshop on Electronics for Particle Physics

Packaging and Interconnects

Grosvenor hotel
1-9 Grosvenor Terrace, Glasgow G12 0TB.

Friday 4 October

09:00

Packaging and Interconnects

Session | **Location:** Grosvenor Suite Theatre | **Conveners:** Magnus Hansen, Ken Wyllie

09:00–09:20

3D Integration of Pixel Readout Chips using Through-Silicon-Vias

Speaker

Francisco Piernas Diaz

09:20–09:40

Development of a novel low-mass module flex PCB using nano-wire-based flip-chip interconnection

Speaker

Julian Weick

09:40–10:00

Design, Production and Testing of ATLAS ITk Strip Bus Tapes

Speaker

Anthony Weidberg

10:00